



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Leung, M.S.

Confirmation No. 8955

Serial No. 10/666,399

Examiner: Le, Thao X.

Filed: Sept. 18, 2003

Art Unit: 2814

Docket No. P0298US-7

Customer No. 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP RCE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

In response to the Office Action mailed on February 28, 2006, please amend the above-identified application as follows:

AMENDMENTS TO THE SPECIFICATION begin on page 2 of this paper.

AMENDMENTS TO THE CLAIMS are reflected in the listing of claims which begin on page 7 of this paper.

REMARKS AND ARGUMENTS begin on page 15 of this paper.